

AN2012S, AN2012SB

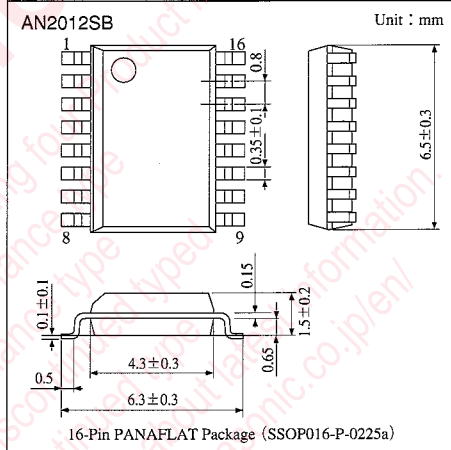
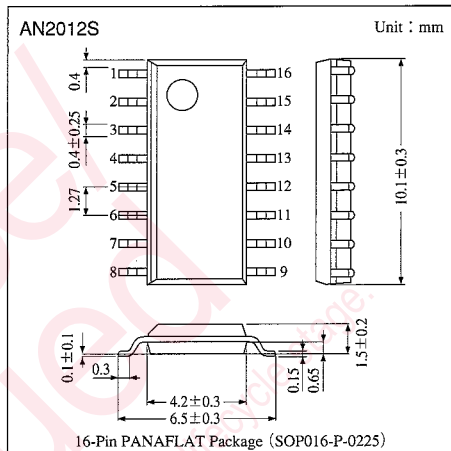
Correlated Double Sampling IC

Overview

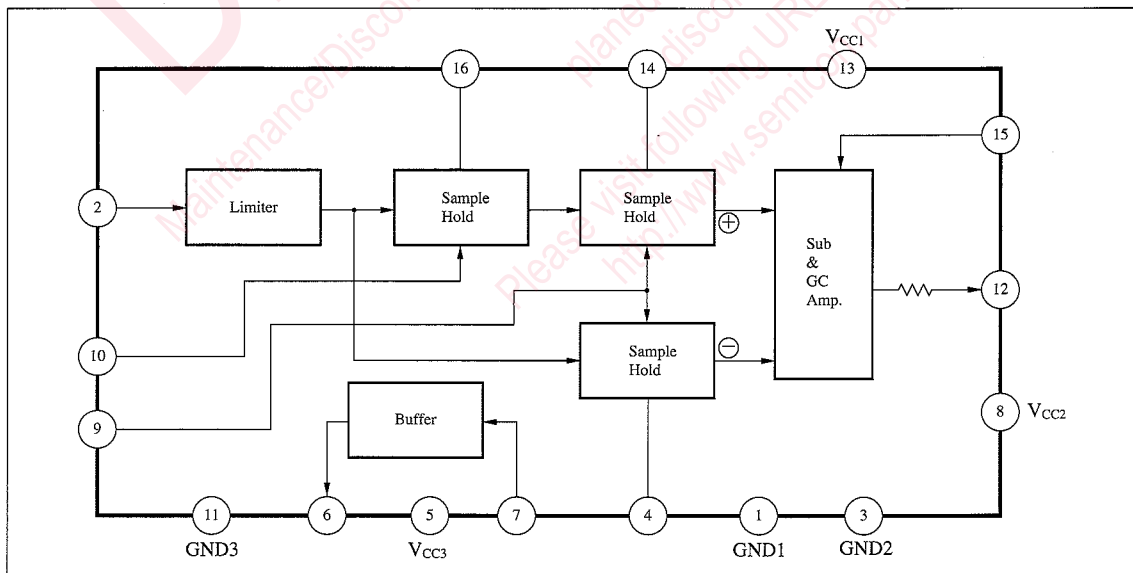
The AN2012S or AN2012SB is integrated circuit that outputs video-signal made from output-signal of CCD image-element by correlated double sampling. Based on the AN2010S, they have the features of high speed sampling and built-in buffering amplifier for trap.

Features

- Available for CCD of up to 710H by using the high-speed sampling circuit
- Gain variable circuit built-in (0.7 to 2 times)
- The sampling pulse is compatible with CMOS level.
- Trapping buffer circuit built-in
- Small package of 0.65mm pin employed (only in AN2012SB)



Block Diagram



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